



Semiconductor Device Type: OA / SN / SM (C2X) 008 SOIC .150in.(3.90mm) matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	Contained in Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight	79.8	
Silica, vitreous	60676-86-0	Mold Compound	69.354	54.096	693.542	62.24	Silica, vitreous	60676-86-0	86.91	
Epoxy Resin	Trade Secret	Mold Compound	6.121	4.774	61.207		Epoxy Resin	Trade Secret	7.67	
Phenolic Resin	Trade Secret	Mold Compound	4.078	3.181	40.778		Phenolic Resin	Trade Secret	5.11	
Carbon Black	1333-86-4	Mold Compound	0.247	0.193	2.474		Carbon Black	1333-86-4	0.31	
							<b>Total</b>			<b>100.00</b>
Copper	7440-50-8	Lead Frame	10.031	7.825	100.314	8.19				
Iron	7439-89-6	Lead Frame	0.247	0.192	2.468		(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	0.156	2.000		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.013	0.010	1.31		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.009	0.007	87		Silver	7440-22-4	1.91	
Silver (Ag)	7440-22-4	Die Attach	0.563	0.439	5.625	Zinc	7440-66-6	0.13		
Modified Epoxy Resin	13561-08-5	Die Attach	0.105	0.082	1.050	Phosphorous	7723-14-0	0.08		
Diglycidylether of bisphenol-F	54208-63-8	Die Attach	0.056	0.044	563	<b>Total</b>			<b>100.00</b>	
4-Methyl-2-phenyl-1H-imidazole	827-43-0	Die Attach	0.026	0.020	263	0.59	(mg) Total	Die Attach	% of Total Weight	0.75
Silicon	7440-21-3	Chip (Die)	7.500	5.850	75.000	Silver (Ag)	7440-22-4	75.00		
Copper	7440-50-8	Wire Bond palladium coated copper (CuPd)	0.197	0.153	1.965	Modified Epoxy Resin	13561-08-5	14.00		
Palladium	7440-05-3	Wire Bond palladium coated copper (CuPd)	0.004	0.003	35	Diglycidylether of bisphenol-F	54208-63-8	7.50		
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	0.975	12.500	4-Methyl-2-phenyl-1H-imidazole	827-43-0	3.50		
<b>0.0780 g Total Mass</b>			<b>TOTALS:</b>	<b>100.000</b>	<b>78.000</b>	<b>1,000,000</b>	<b>Total</b>			<b>100.00</b>
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)										
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and/or analytical test data.										
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.										
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <a href="http://ul.com/globaleng/pages/offering/industries/chemicals/plastics/">http://ul.com/globaleng/pages/offering/industries/chemicals/plastics/</a>										
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.										
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <a href="http://echa.europa.eu/web/guest/candidate-list-table">http://echa.europa.eu/web/guest/candidate-list-table</a>										
						5.85	Total (mg)	Chip (Die)	% of Total Weight	7.5
							Doped Silicon	7440-21-3	100.00	
						<b>Total</b>			<b>100.00</b>	
						0.16	(mg) Total	Wire Bond - Copper, palladium coated (CuPd)	% of Total Weight	0.2
							Copper	7440-50-8	98.25	
							Palladium	7440-05-3	1.75	
						<b>Total</b>			<b>100.00</b>	
						0.98	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.25
							Tin	7440-31-5	100.00	
						<b>Total</b>			<b>100.00</b>	
						<b>78.000</b>				<b>100.000</b>